

IN THE ABSTRACT

Please replace the abstract with the following abstract.

--METHOD OF MANUFACTURING A WAFER ASSEMBLY

ABSTRACT

A method of manufacturing a wafer assembly involves a chip wafer onto which a cover wafer is deposited, the chip wafer includes an active face and an inactive face, the active face includes chip elements, the cover wafer being provided with a chip-element-receiving cavity located above a chip element, the method involves the following steps: a cover-wafer-depositing step, in which a cover wafer is deposited on the active face so as to obtain a wafer assembly, the cover wafer being provided with plurality of chip-receiving cavities, a chip-receiving cavity being located above a chip element, the cover wafer being made of an organic material, and a wafer assembly thinning step, in which the inactive face of the chip wafer is thinned.--